**Fabrication Parameters:**

- **Thickness:** 0.002
- **Silkscreen:** BOTH
- **Soldermask:** BOTH
- **Copper Weight:** 1 OZ [EXT] / 1 OZ [INT]
- **Design Type:** HEI
- **New Tracegap:** 0.0006 / 0.0035
- **Laser Count:** 0 LAYERS

**Notes: Unless Otherwise Specified**

1. **Material:** All materials, including but not limited to base laminate, bonding materials and soldermask coating forming the finished printed circuit board shall meet UL-796 requirements and be RoHS compliant and have a flammability of UL94V-0.
2. **Base Laminate:** Plastics sheet, laminate metal clad, two sides, base material non-type PE-4 glass epoxy resin, copper-clad in accordance with 6 layer stack-up, compliant with lead free process.
3. **Soldermask:** Soldermask over bare copper (SMBC) using liquid photo-imageable soldermask in accordance with IPC-4900.
4. **Plating:** Holes requiring plating, see hole chart, to have 1 oz. (0.0014) min. min. thickness of copper.
5. **Finish:** Plate with bare compliant, immersion silver preferred, immersion tin or SnAgCu, with max tins, 0.003" / 0.005" their new all exposed areas as needed, no active fluxes are acceptable.
6. **Legend:** IF REQUIRED, SILKSCREEN LEGEND(S) WITH WHITE NON-CONDUCTIVE EPOXY IN ACCORDANCE WITH IPC-SM-840.
7. **Markings:** BOARD MUST Bear vendor's identification code, letter or numeric, non-conductive only.
8. **Location Option:** Location optional.
9. **Workmanship:** PC boards shall be manufactured for IPC-A-600 Class 2 requirements or better.
10. **Documentation:** PCB vendor is required to return any and all documents supplied or ultimately purchased by Texas Instruments upon completion of purchase order.
11. **Drill Sizes:** Hole diameters shown are finished sizes after plating unless otherwise noted.
12. **Finish Solder:** Any metal in solder area including part numbers, datecode and revision letters must be covered with soldermask.
13. **Process Changes:** No dimensional material, or process changes are allowed without prior written permission from Texas Instruments.

**Drill Chart: Top to Bottom**

*All Units are in Milns*

<table>
<thead>
<tr>
<th>FIGURE</th>
<th>SIZE</th>
<th>TOLERANCE</th>
<th>PLATED</th>
<th>QTY</th>
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